

Component Placing, Electrical

Applicable for W550i, W550c

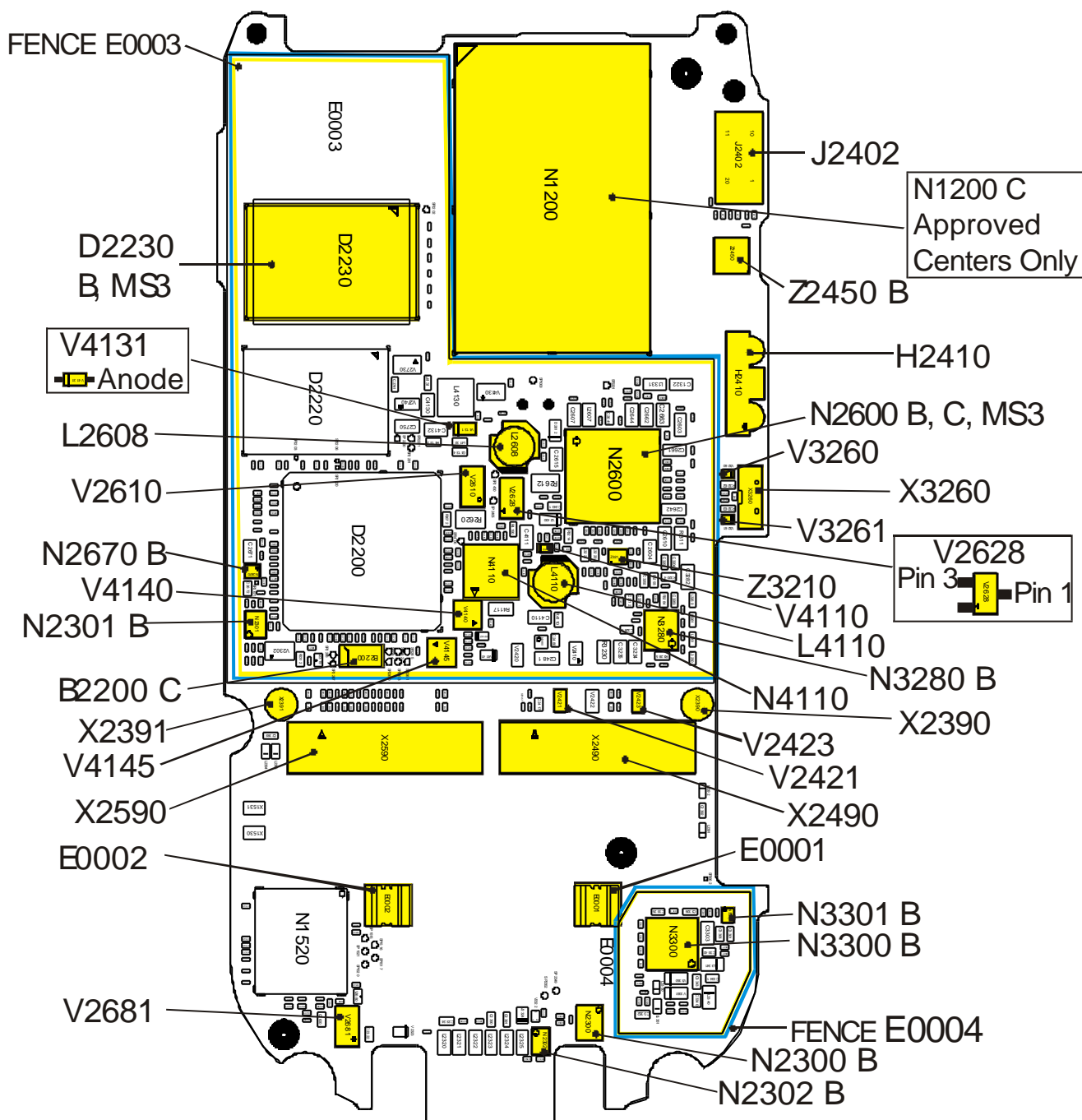
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1078-2/FEA 201

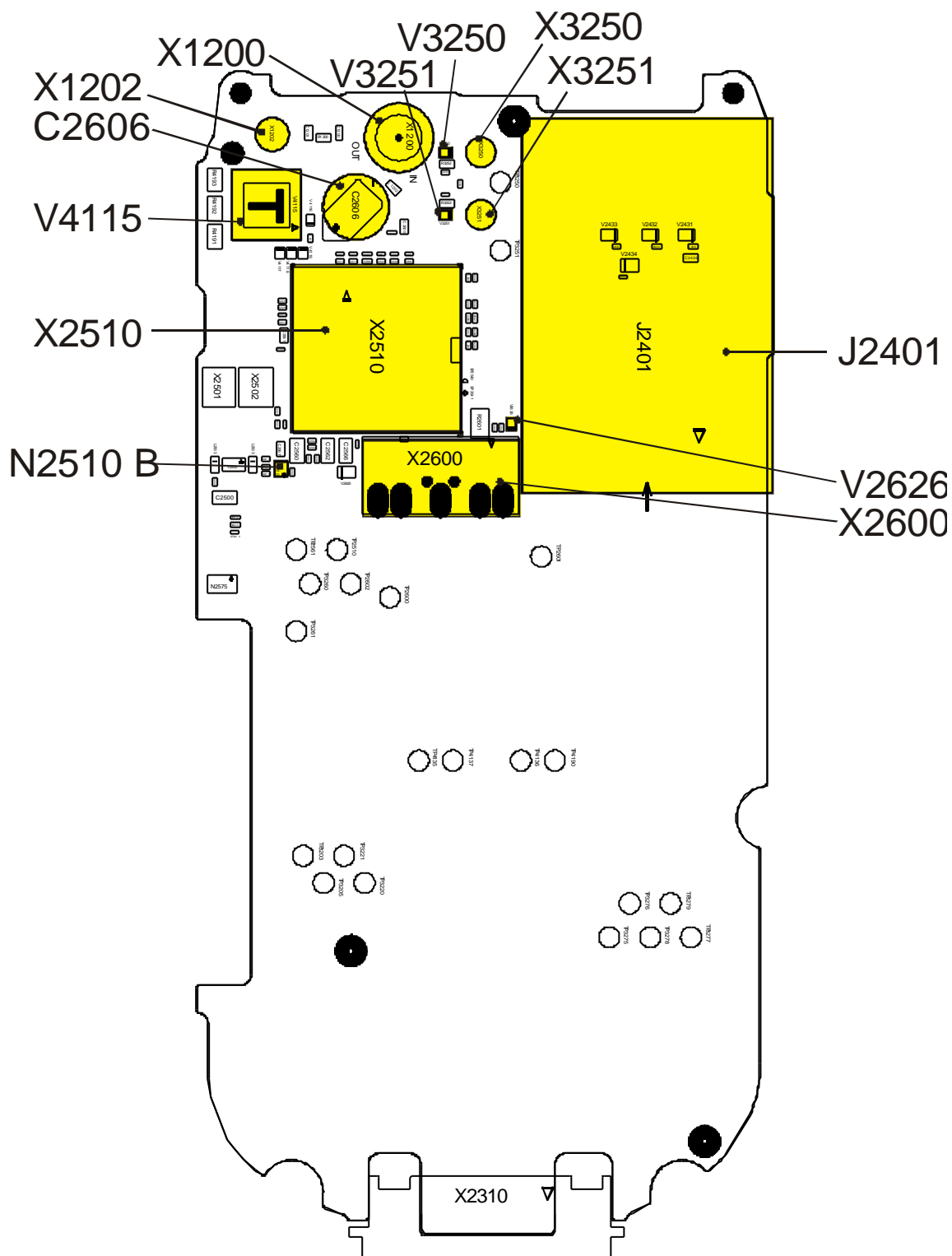
1 Component Placing (Primary Side)



B - BGA Rework Equipment Required
C - Calibration Required
MS - Moisture Sensitive - Baking Required



2 Component Placing (Secondary Side)



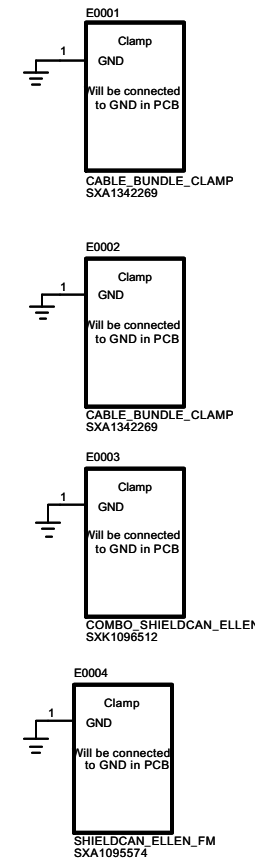
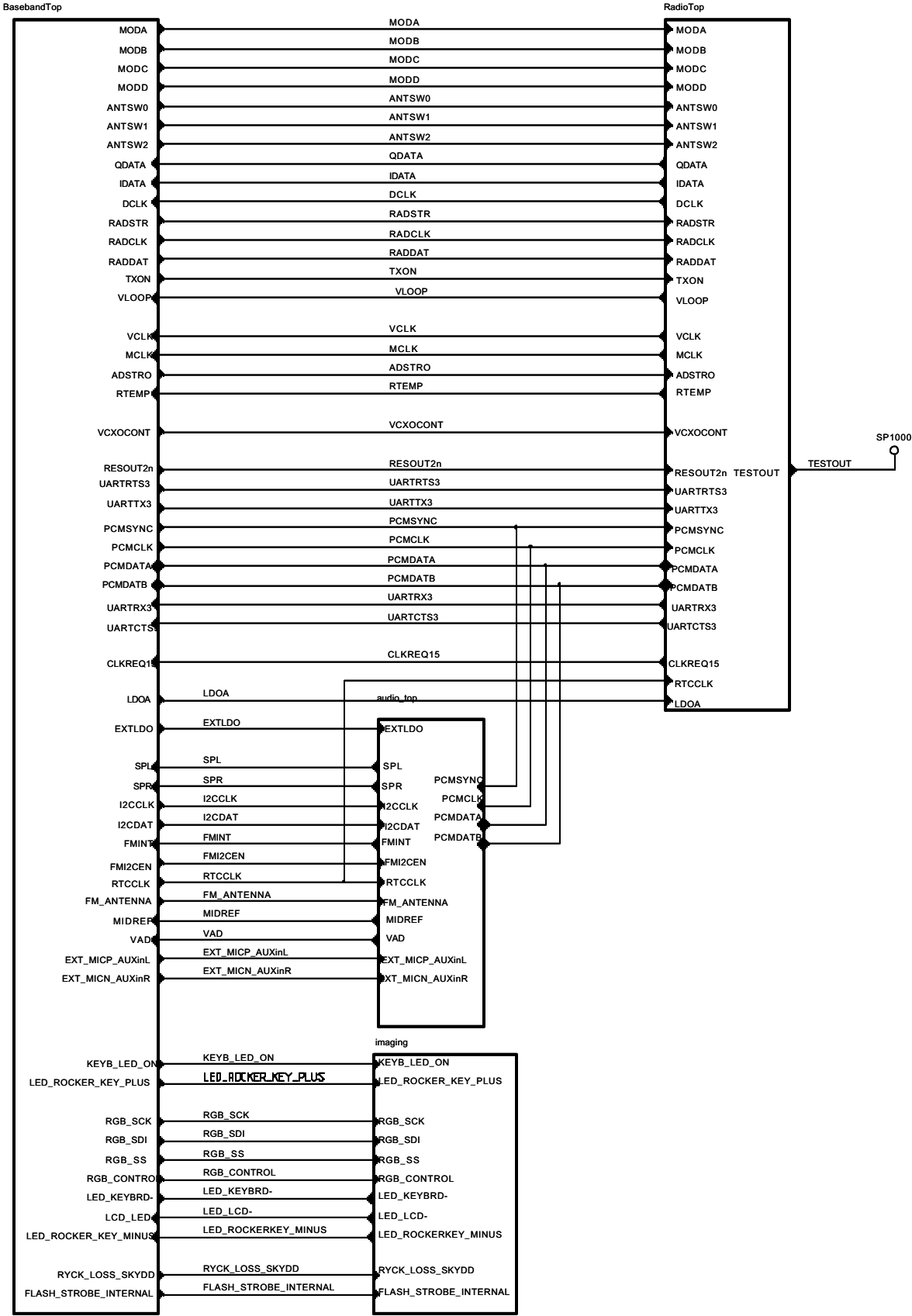
B - BGA Rework Equipment Required
C - Calibration Required
MS - Moisture Sensitive - Baking Required

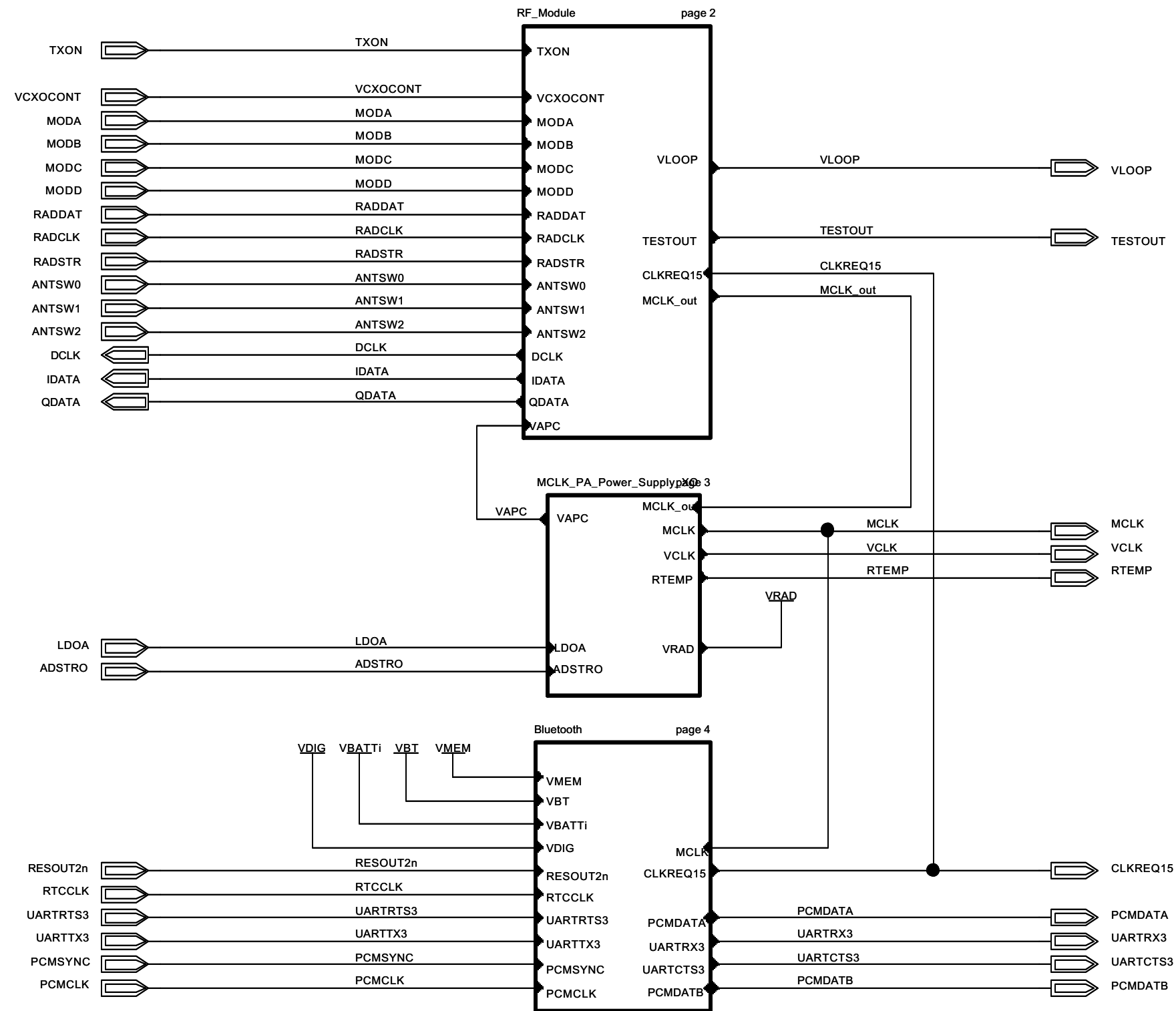
3 Schematics

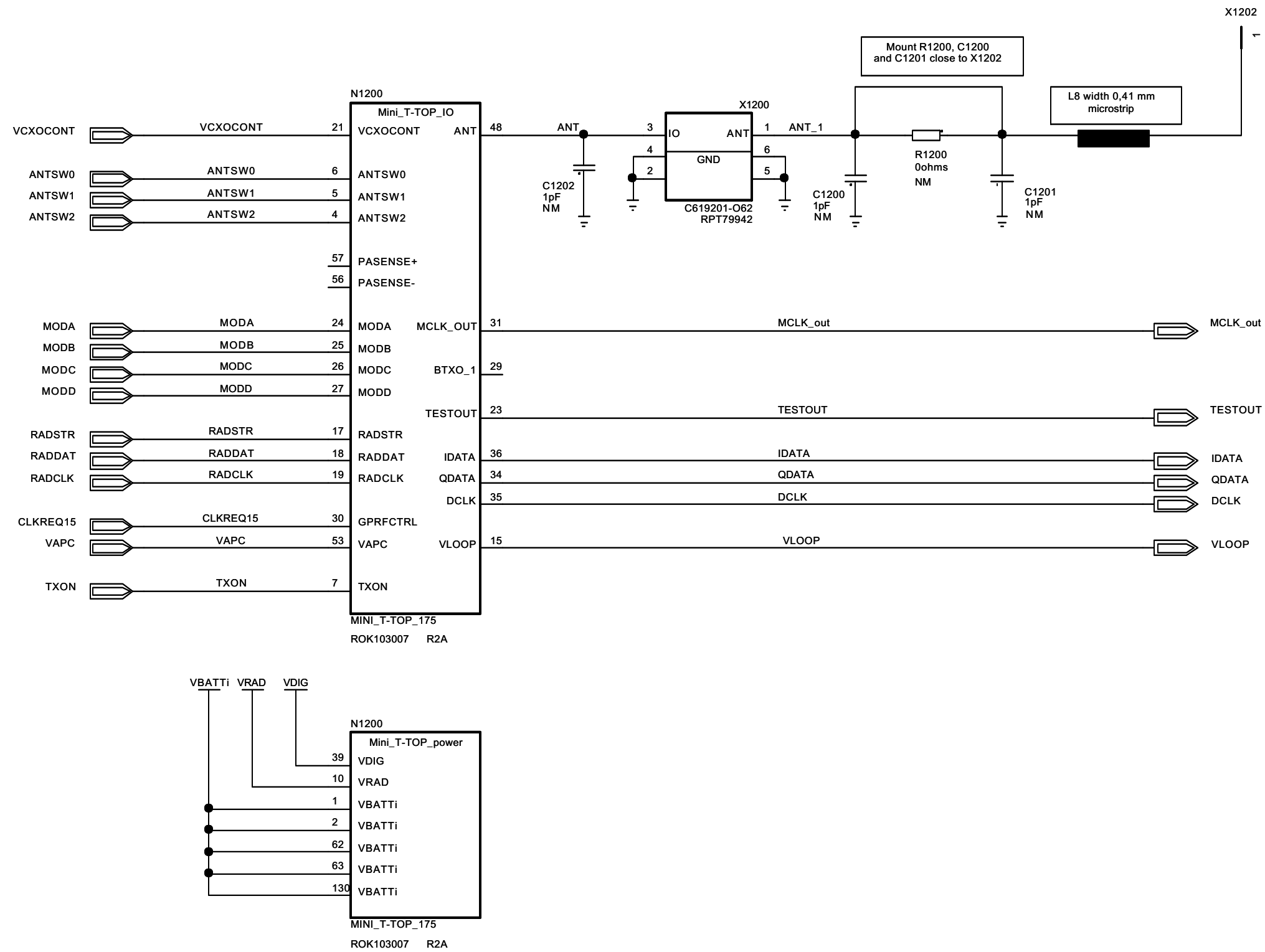
The schematic's is divided in:

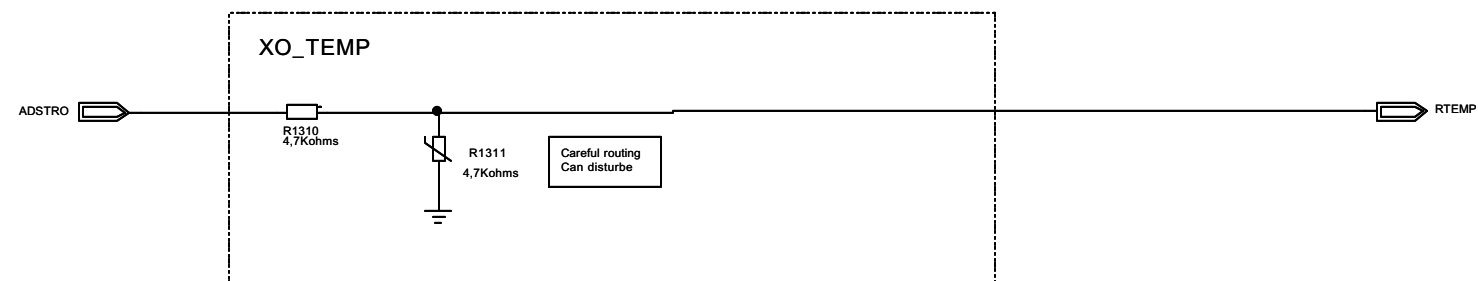
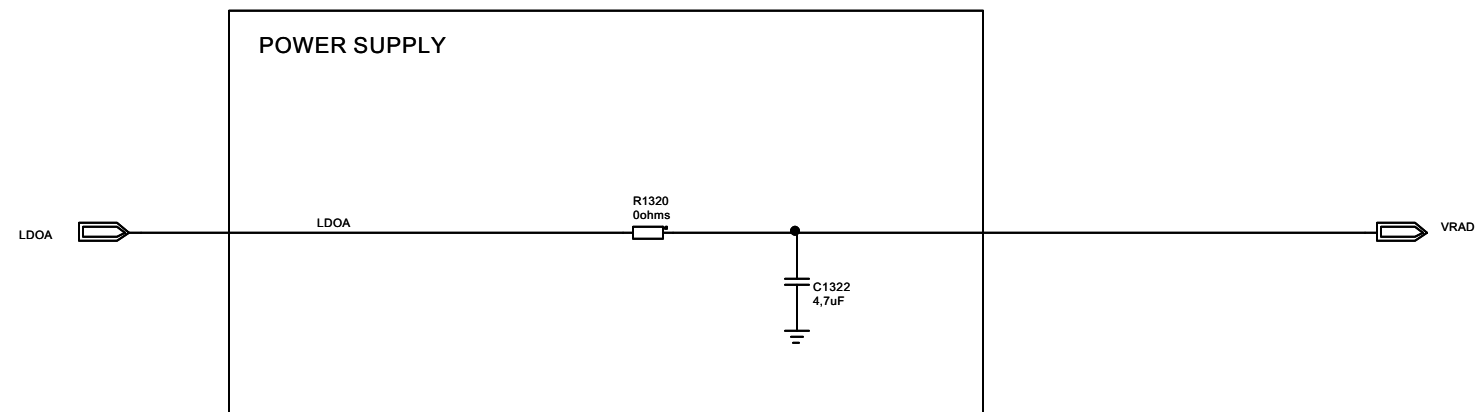
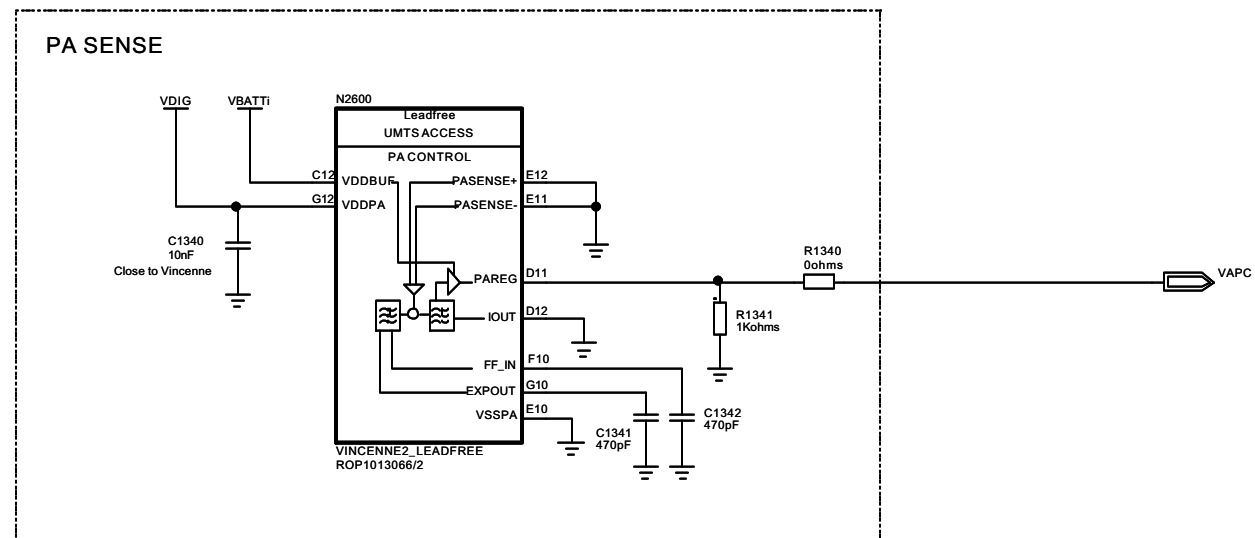
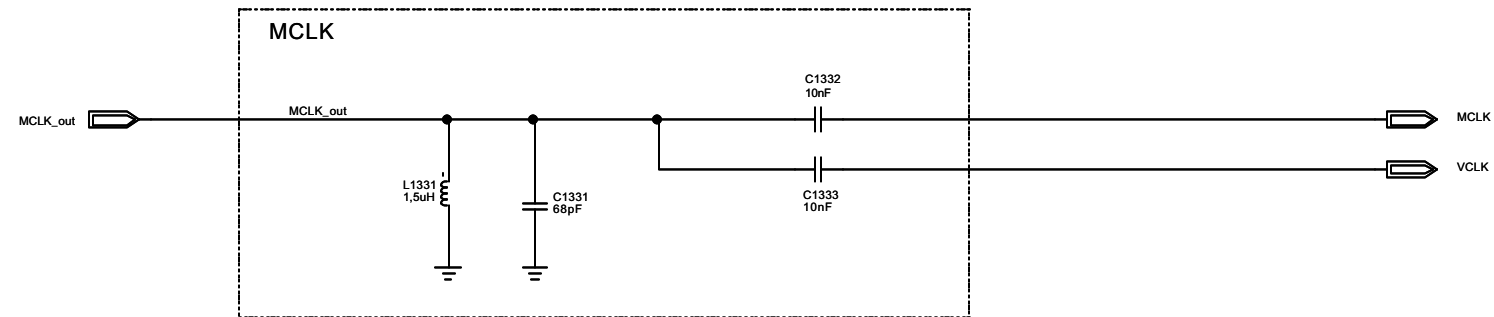
- Overview of signals 1911
- Radio part 1/1911
- Logical part 2/1911
- Audio part 3/1911
- Imaging part 4/1911

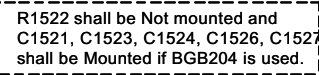
TVK: Layer information
Layer 1: Signal
Layer 2: Signal
Layer 3: Signal and supply lines
Layer 4: GND main
Layer 5: Striplines, supply lines and
signal which need careful routing
Layer 6: GND
Layer 7: Signal
Layer 8: Signal

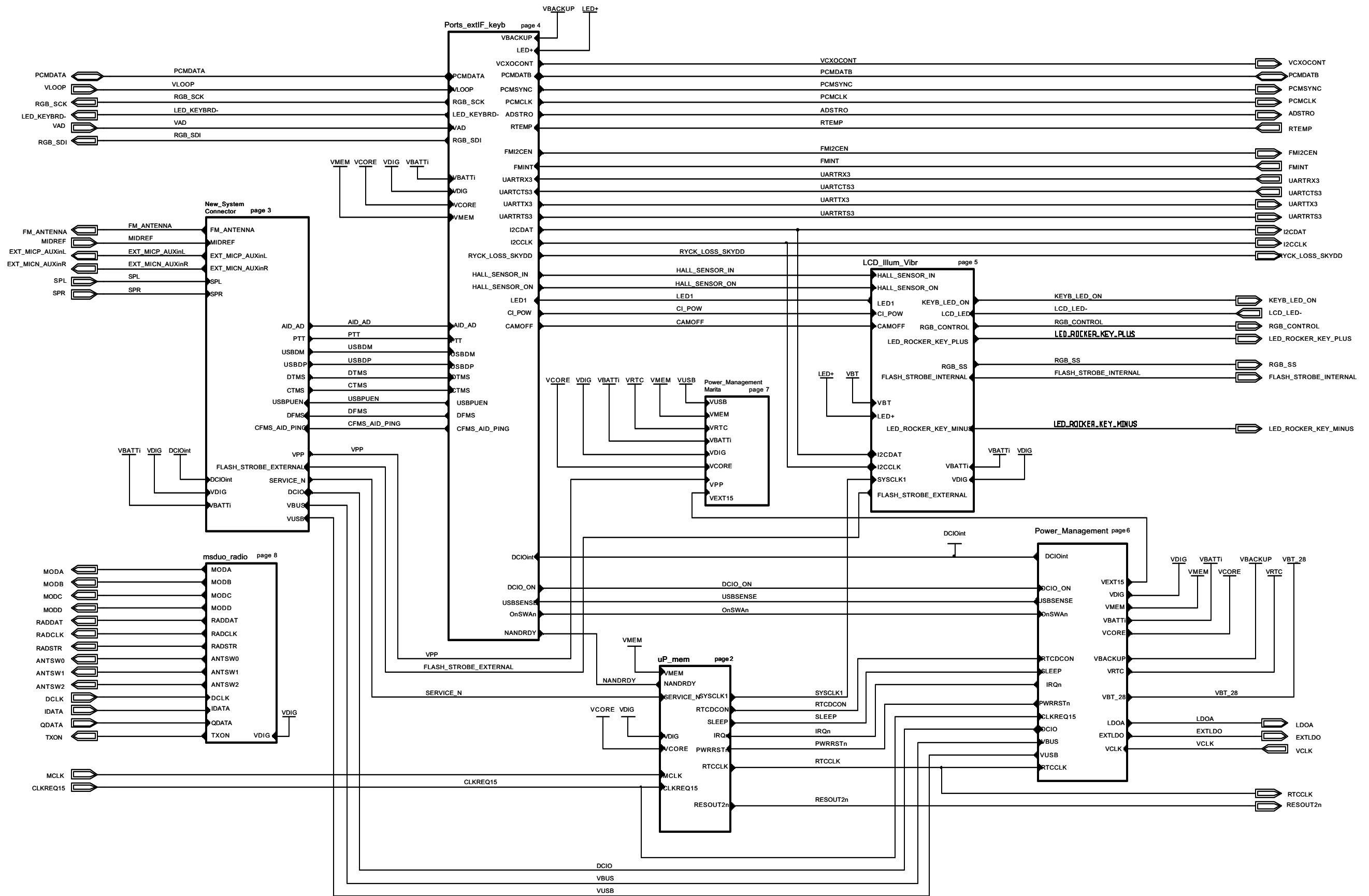


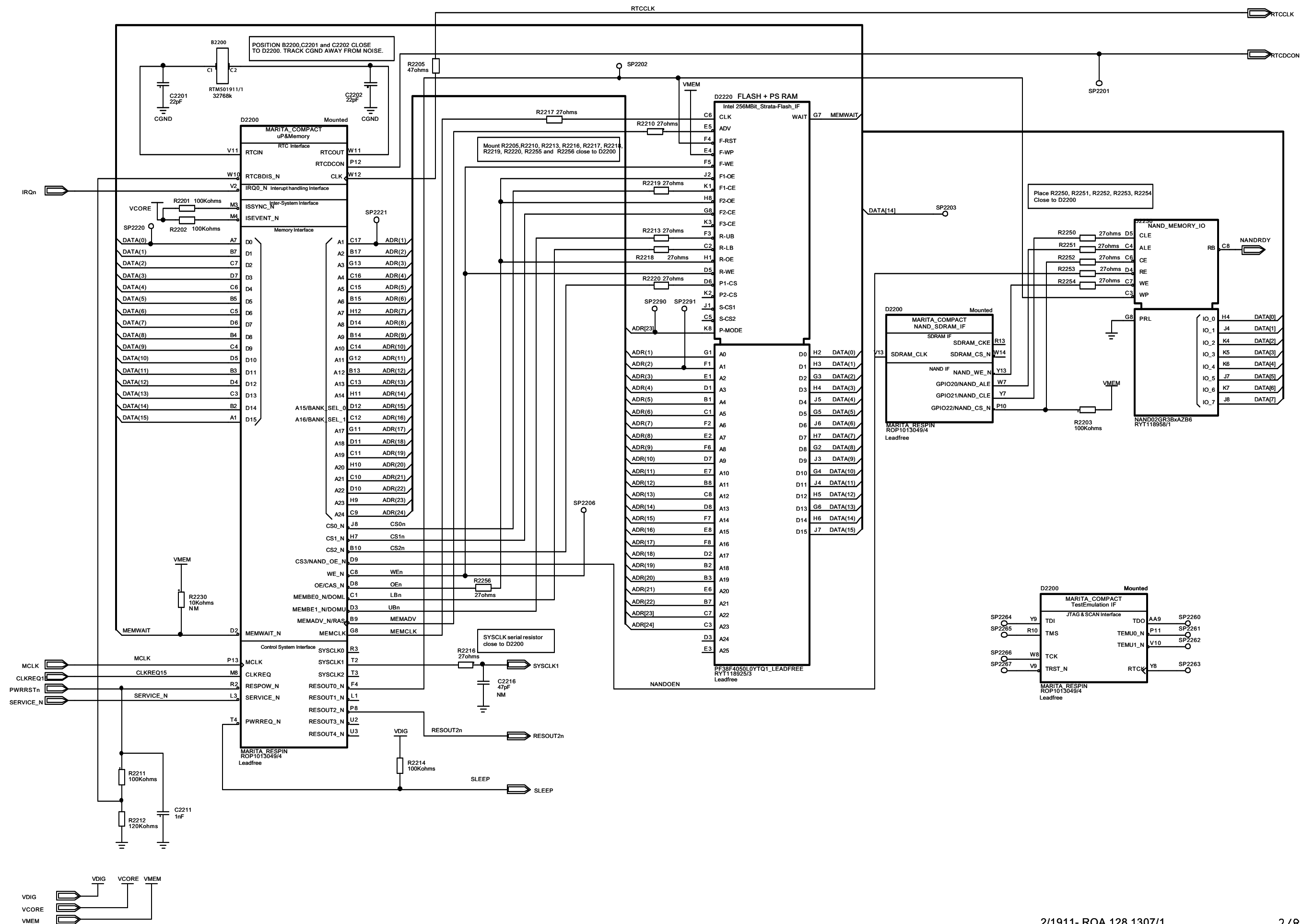


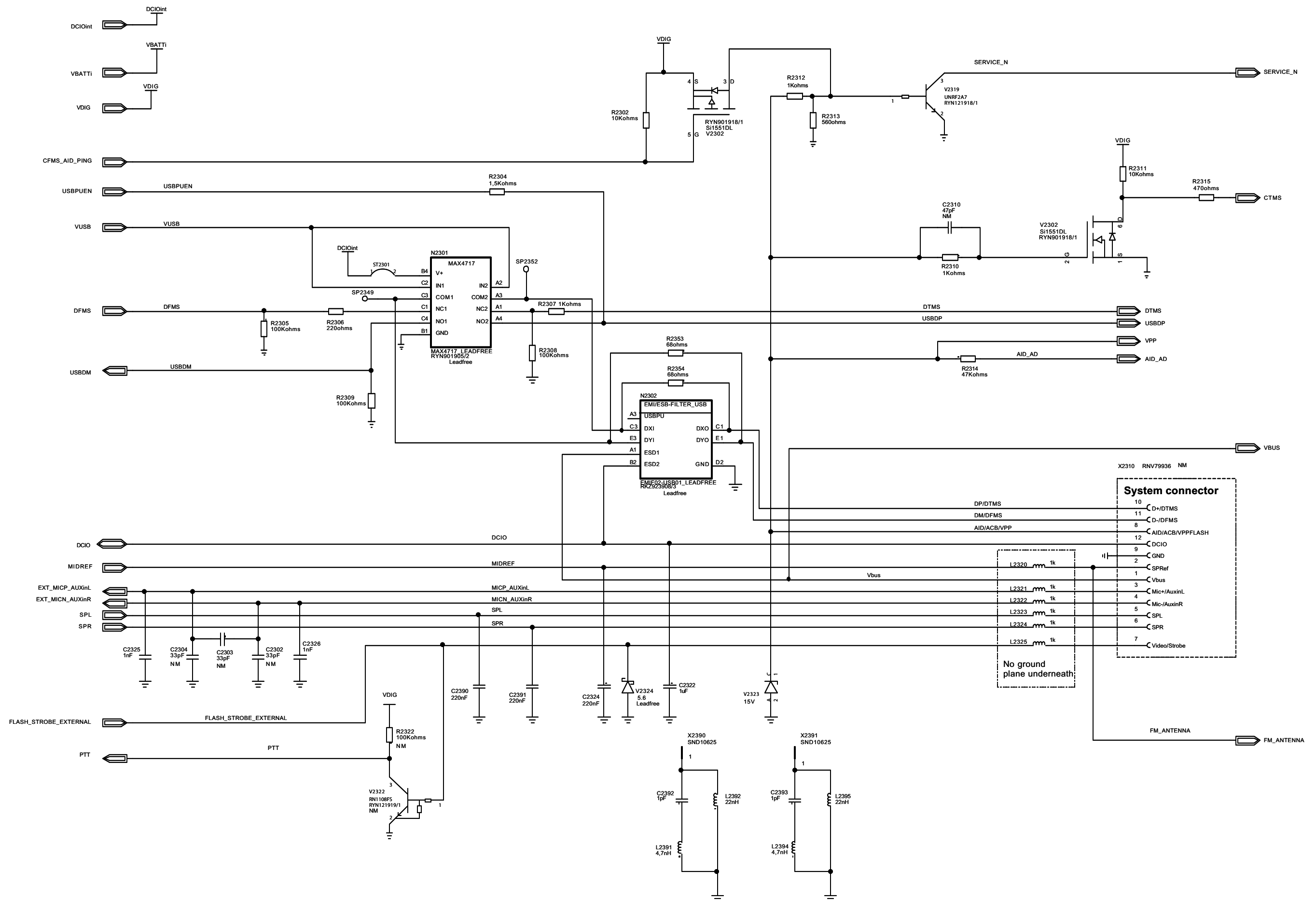


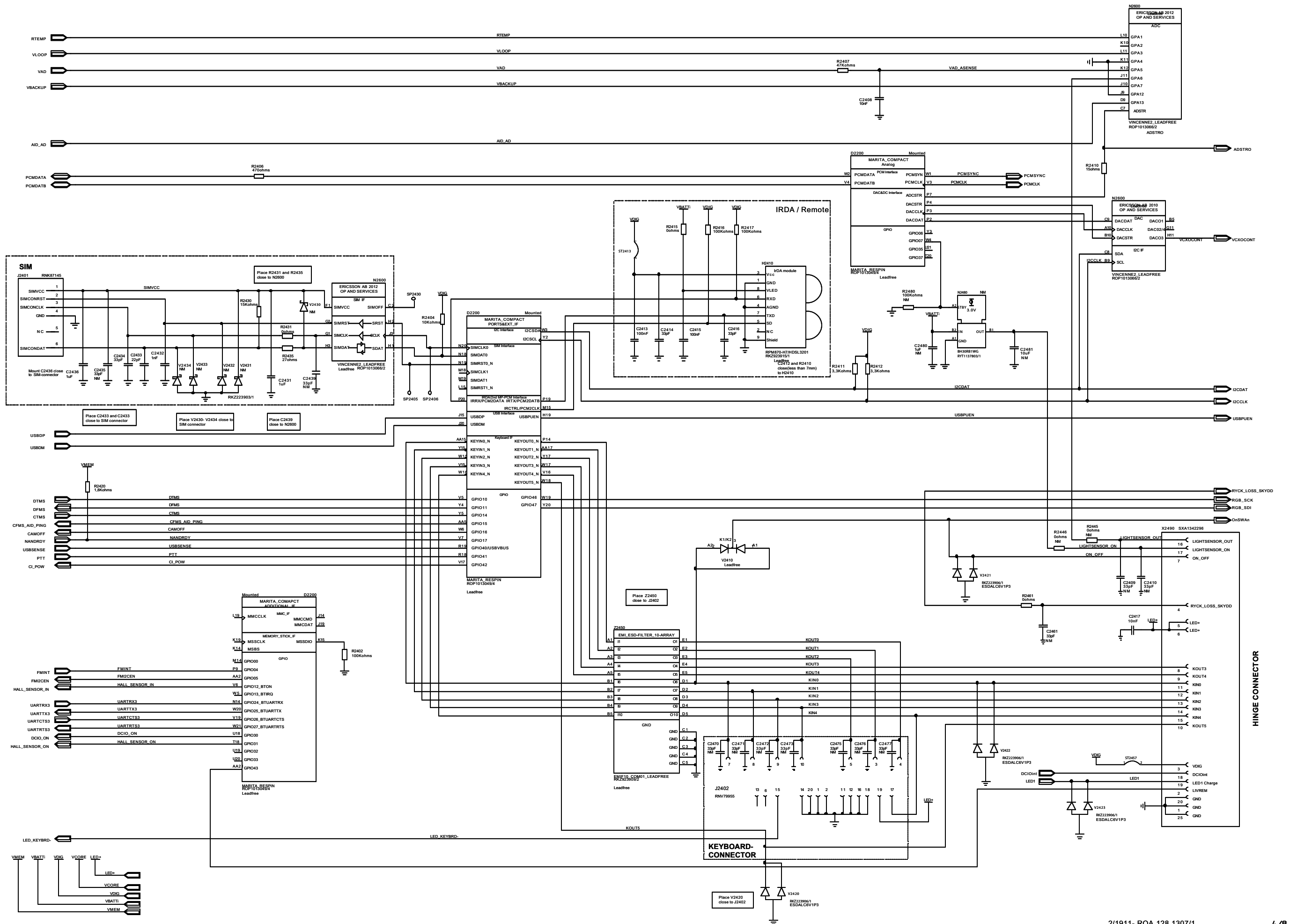


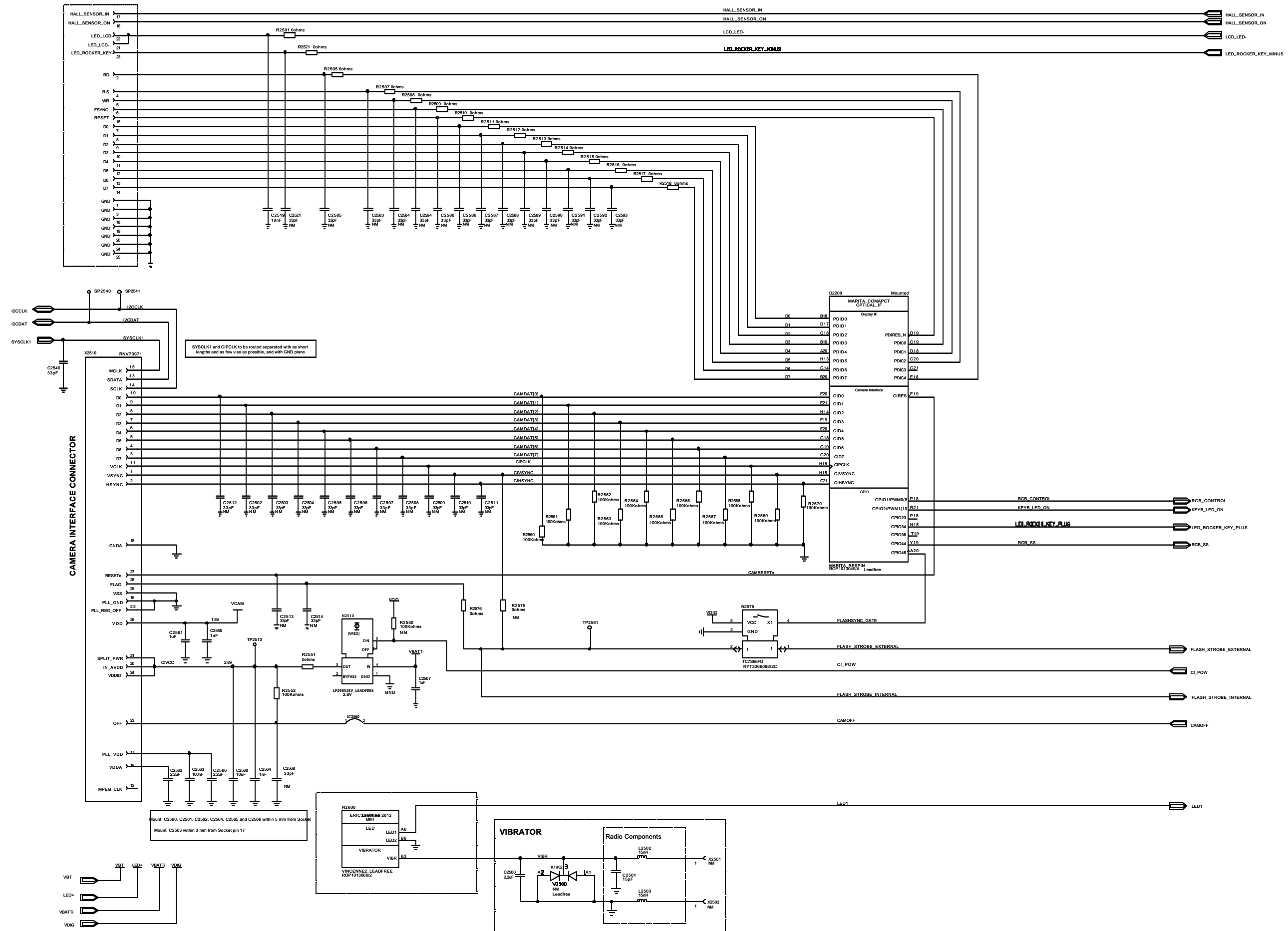


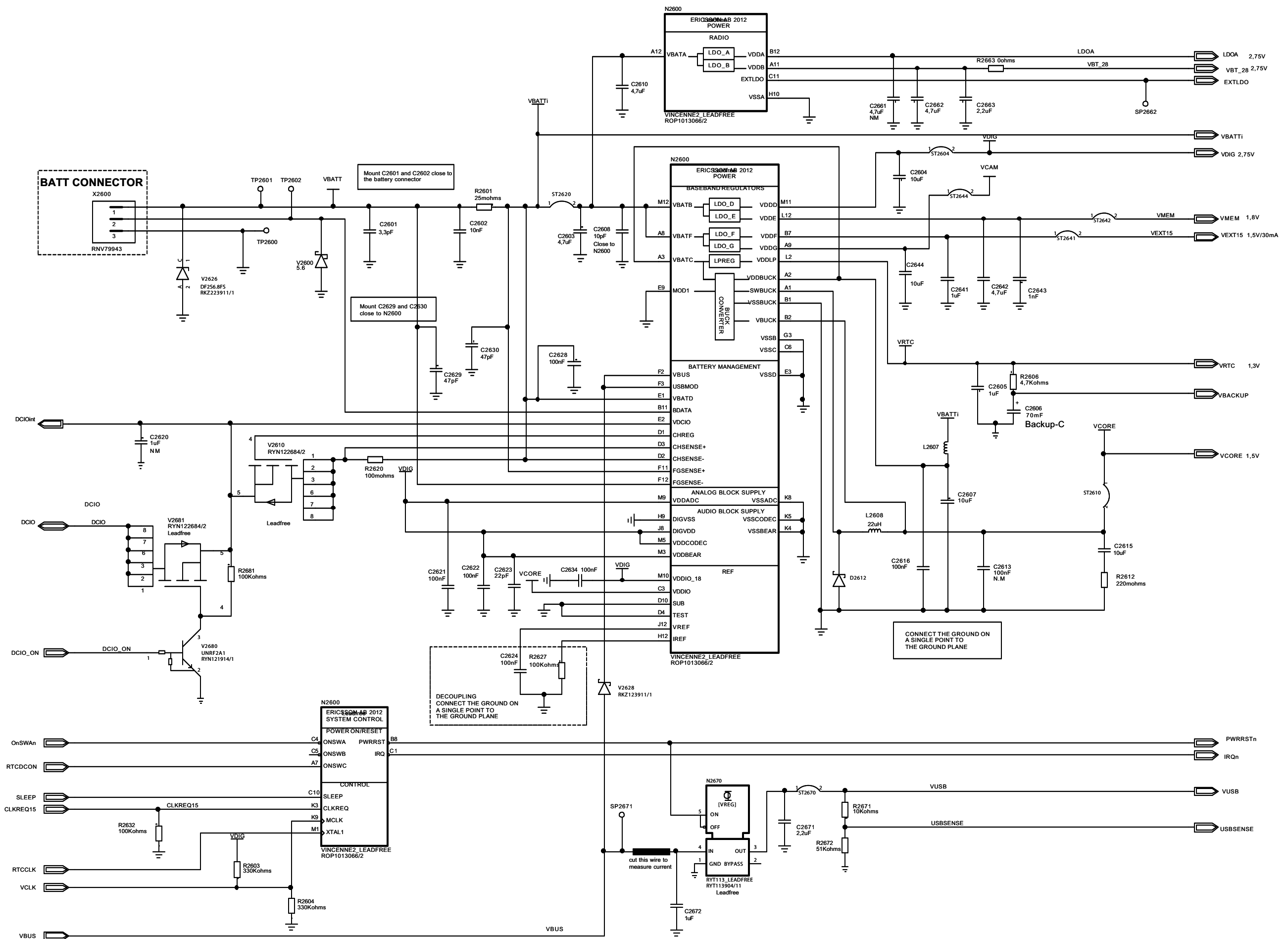


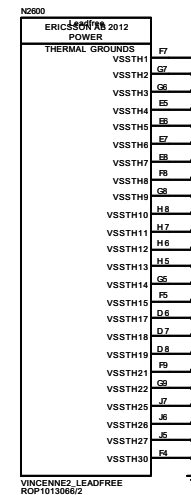
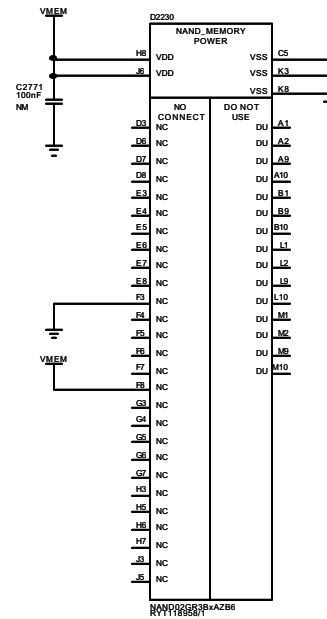
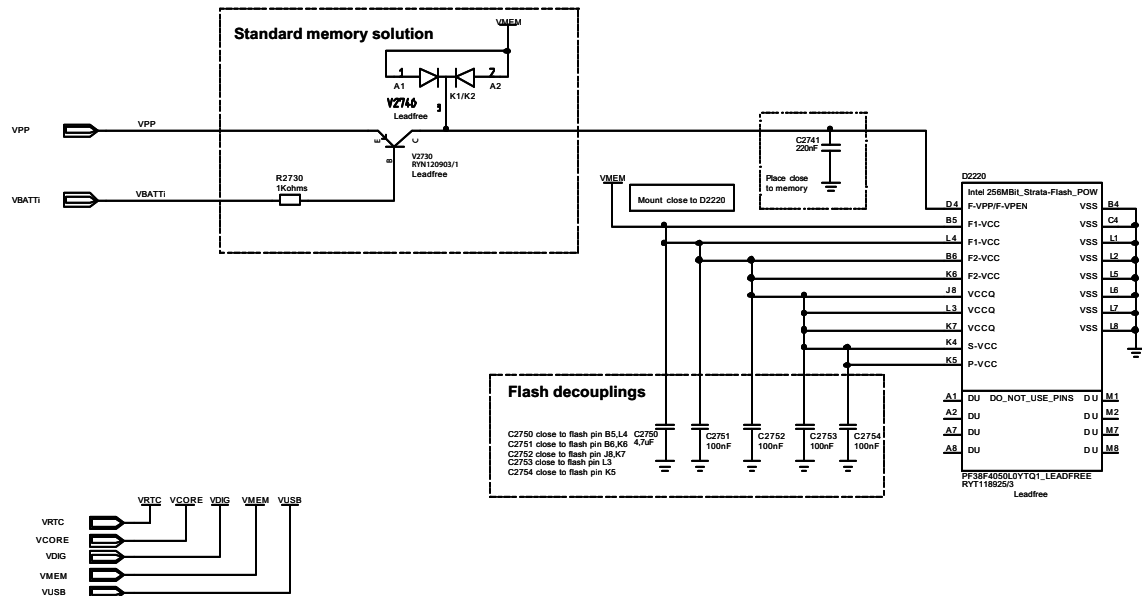
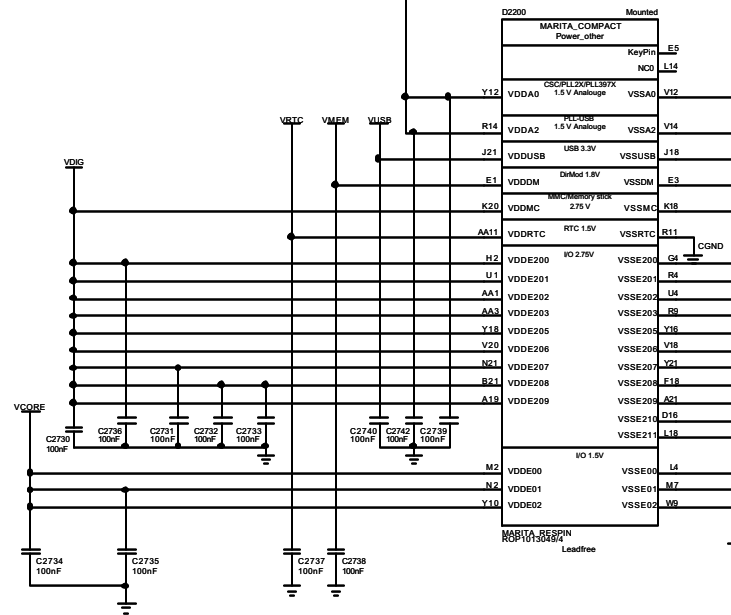
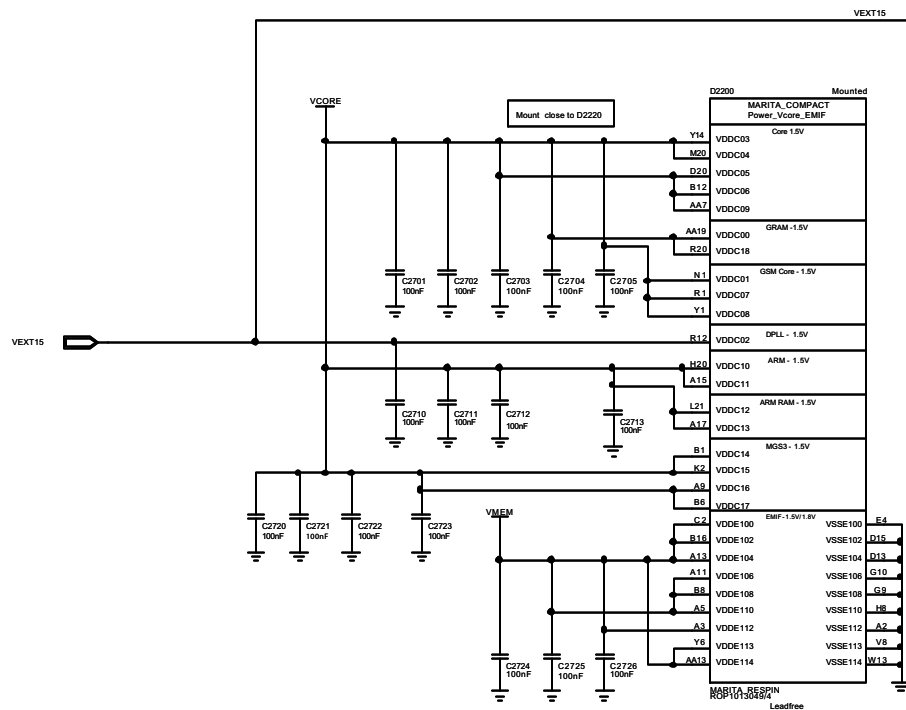


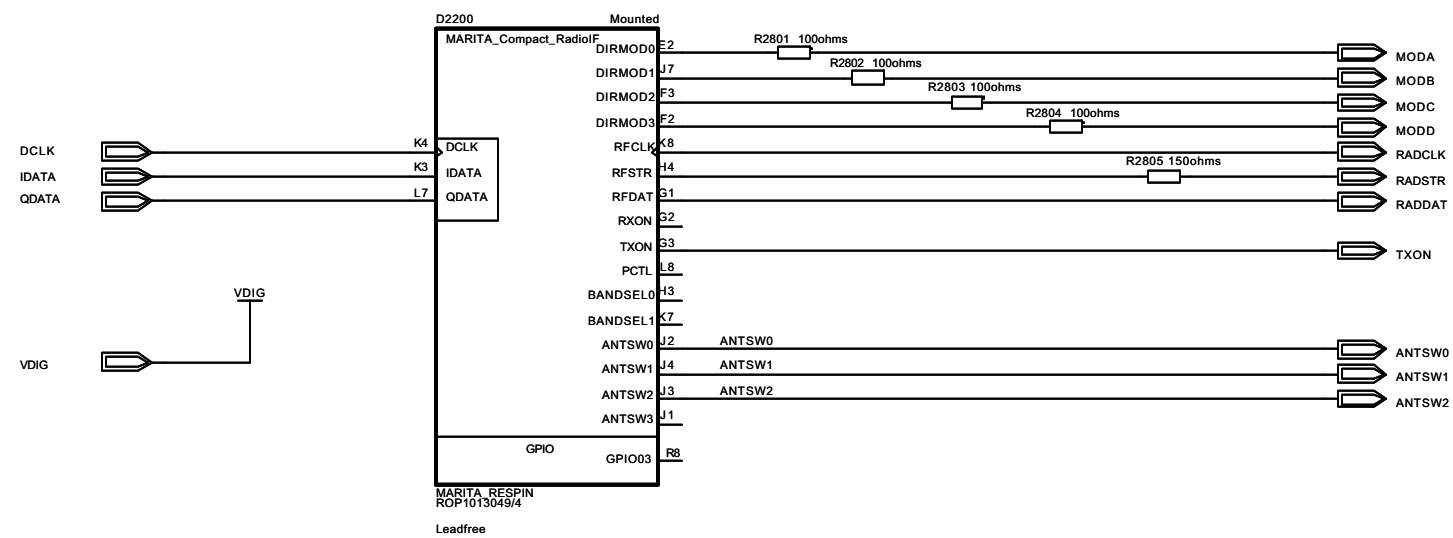


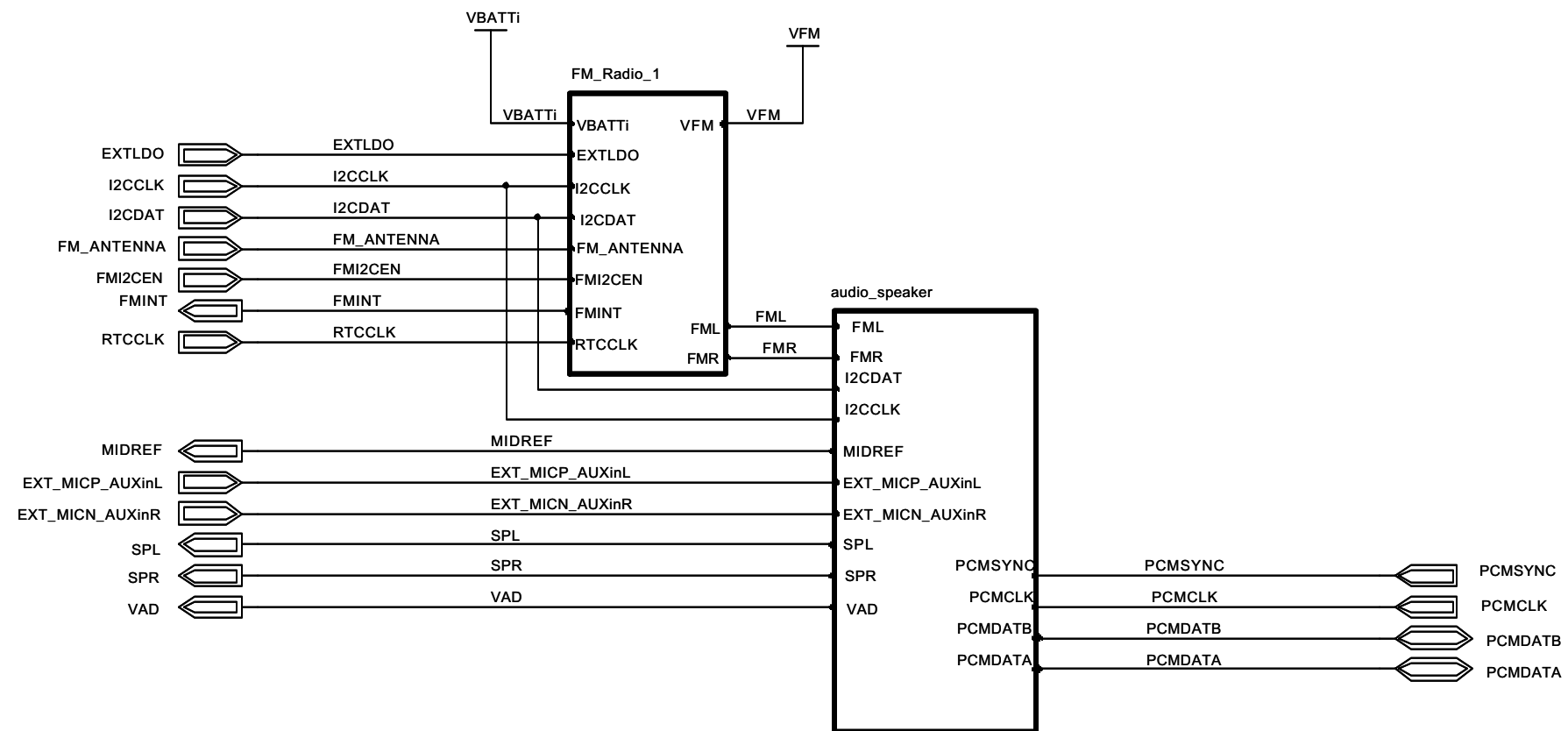


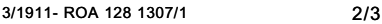


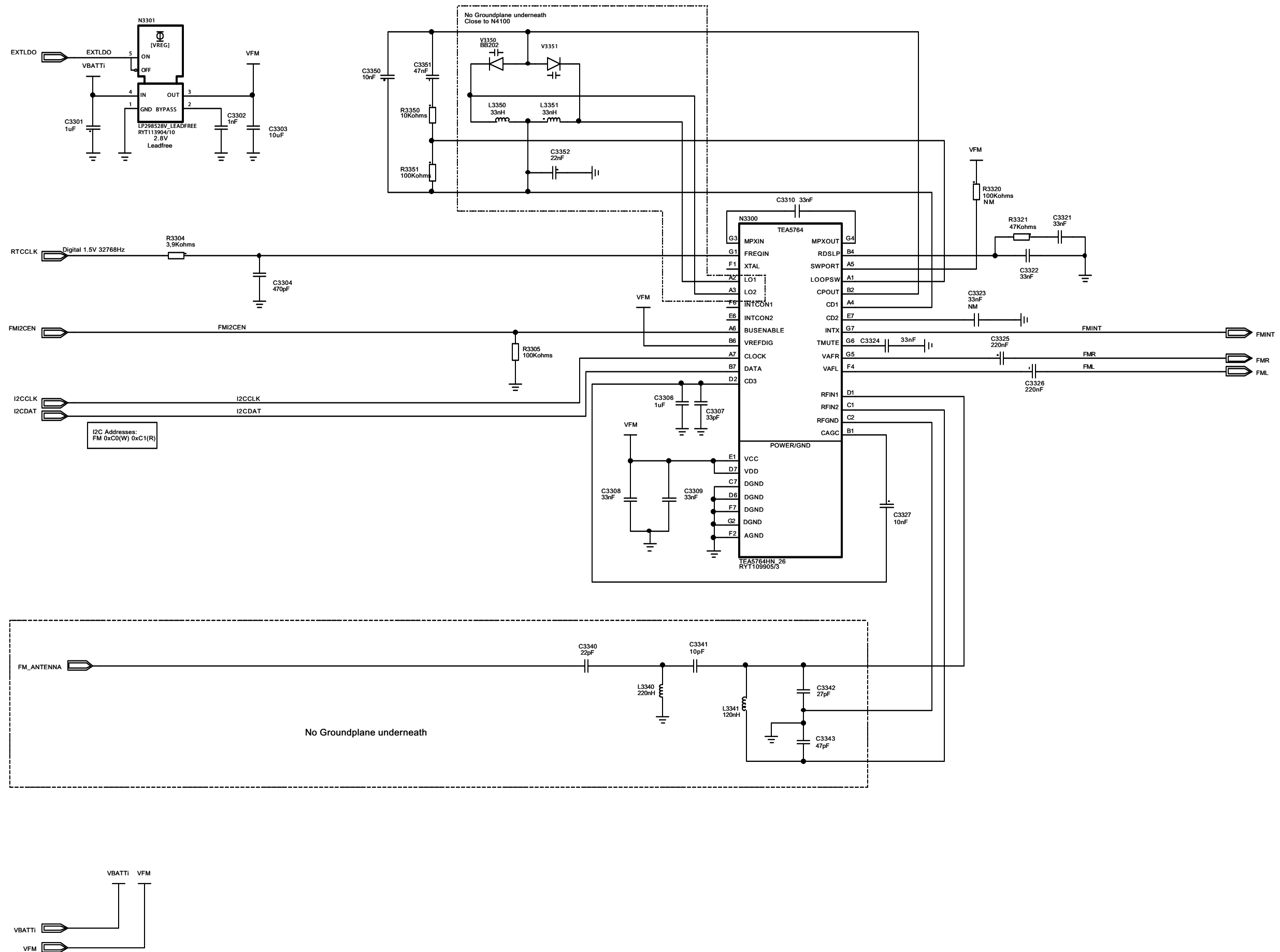














4 Revision History

Rev.	Date	Changes / Comments
A	2005-Sep-16	Initial Release
B	2005-Oct-28	Footer information corrected
C	2005-Nov-02	Schematics added